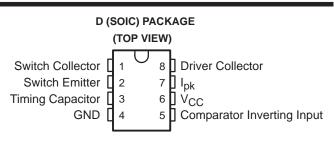
MC33063A-Q1 1.5-A PEAK BOOST/BUCK/INVERTING SWITCHING REGULATOR

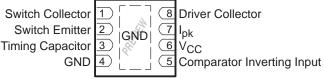
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Qualification in Accordance With AEC-Q100†

- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Wide Input Voltage Range . . . 3 V to 40 V
- High Output Switch Current . . . Up to 1.5 A
- Adjustable Output Voltage
- Oscillator Frequency . . . Up to 100 kHz
- Precision Internal Reference . . . 2%
- Short-Circuit Current Limiting
- Low Standby Current



DRJ (QFN) PACKAGE (TOP VIEW) tor 1 8 Driver Co



description/ordering information

The MC33063A is an easy-to-use IC containing all the primary circuitry needed for building simple dc-dc converters. This device primarily consists of an internal temperature-compensated reference, a comparator, an oscillator, a PWM controller with active current limiting, a driver, and a high-current output switch; thus, the device requires minimal external components to build converters in the boost, buck, and inverting topologies.

The MC33063A is characterized for operation from -40°C to 125°C.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
4000 to 40500	QFN (DRJ)	Reel of 1000	MC33063AQDRJR	PREVIEW	
-40°C to 125°C	SOIC (D)	Reel of 2500	MC33063AQDR	33063AQ	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

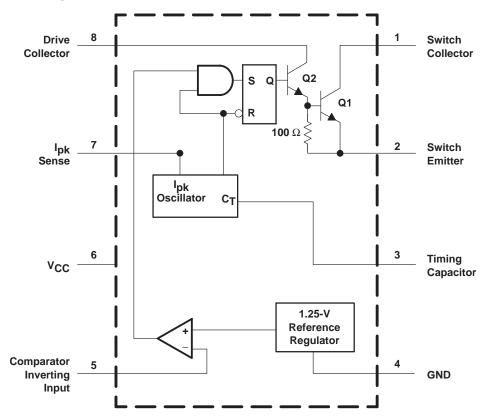


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[†] Contact factory for details. Q100 qualification data available on request.

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	40 V
Comparator Inverting Input voltage range, VIR	
Switch Collector voltage, V _{C(switch)}	40V
Switch Emitter voltage (V _{PIN1} = 40 V), V _{E(switch)}	40V
Switch Collector to Switch Emitter voltage, V _{CE(switch)}	40V
Driver Collector voltage, V _{C(driver)}	40V
Driver Collector current, I _{C(driver)}	
Switch current, I _{SW}	
Package thermal impedance, θ _{JA} (see Notes 1 and 2): D package	97°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



MC33063A-Q1 1.5-A PEAK BOOST/BUCK/INVERTING SWITCHING REGULATOR

SLLS654A - APRIL 2005 - REVISED JANUARY 2007

recommended operating conditions

			MIN	MAX	UNIT
VCC	Supply voltage		3	40	V
TA	Operating free-air temperature range	MC33063A	-40	125	°C

electrical characteristics, $V_{CC} = 5 \text{ V}$, $T_A = \text{full operating range (unless otherwise noted)}$ (see block diagram)

OSCILLATOR

	PARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT
f _{osc}	Oscillator frequency	V _{PIN5} = 0 V, C _T = 1 nF	25°C	24	33	42	kHz
I _{chg}	Charge current	V _{CC} = 5 V to 40 V	25°C	24	35	42	μΑ
Idischg	Discharge current	V _{CC} = 5 V to 40 V	25°C	140	220	260	μΑ
I _{dischg} /I _{chg}	Discharge-to-charge current ratio	V _{PIN7} = V _{CC}	25°C	5.2	6.5	7.5	
V _{lpk}	Current-limit sense voltage	I _{dischg} = I _{chg}	25°C	250	300	350	mV

OUTPUT SWITCH (see Note 3)

PARAMETER		TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT
VCE(sat)	Saturation voltage – Darlington connection	I _{SW} = 1 A, pins 1 and 8 connected	Full range		1	1.3	V
VCE(sat)	Saturation voltage – non-Darlington connection (see Note 4)	Isw = 1 A, RpIN8 = 82 Ω to Vcc, forced $\beta \sim$ 20	Full range		0.45	0.7	V
hFE	DC current gain	I _{SW} = 1 A, V _{CE} = 5 V	25°C	50	75		
IC(off)	Collector off-state current	V _{CE} = 40 V	Full range		0.01	100	μΑ

NOTES: 3. Low duty-cycle pulse testing is used to maintain junction temperature as close to ambient temperature as possible.

4. In the non-Darlington configuration, if the output switch is driven into hard saturation at low switch currents (≤300 mA) and high driver currents (≥30 mA), it may take up to 2 µs for the switch to come out of saturation. This condition effectively shortens the off time at frequencies ≥30 kHz, becoming magnified as temperature increases. The following output drive condition is recommended in the non-Darlington configuration:

Forced β of output switch = I_{C,SW} / (I_{C,driver} - 7 mA) \geq 10,

where \sim 7 mA is required by the 100- Ω resistor in the emitter of the driver to forward bias the V_{be} of the switch.

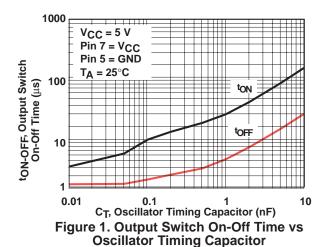
COMPARATOR

PARAMETER		PARAMETER TEST CONDITIONS		MIN	TYP	MAX	UNIT
			25°C	1.225	1.25	1.275	
V _{th}	Threshold voltage		Full range	1.21		1.29	V
ΔV_{th}	Threshold-voltage line regulation	V _{CC} = 5 V to 40 V	Full range		1.4	5	mV
I _{IB}	Input bias current	V _{IN} = 0 V	Full range		-20	-400	nA

TOTAL DEVICE

PARAMETER	TEST CONDITIONS	TA	MIN	MAX	UNIT
ICC Supply current	V_{CC} = 5 V to 40 V, C_T = 1 nF, V_{PIN7} = V_{CC} , V_{PIN5} > V_{th} , V_{PIN2} = GND, all other pins open	Full range		4	mA





1.8 $V_{CC} = 5 V$ 1.7 VCE(SAT), Output Switch Saturation Voltage (V) Pin 1, 7, 8 = V_{CC} Pin 3, 5 = GND 1.6 T_A = 25°C 1.5 1.4 1.3 1.2 1.1 0.2 0.8 0 0.4 0.6 1.2 1.4 1.6 IE, Emitter Current (A)

Figure 2. Output Switch Saturation Voltage vs Emitter Current (Emitter-Follower Configuration)

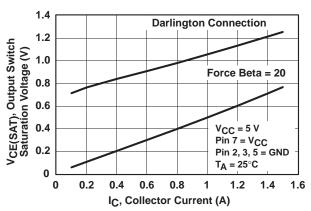


Figure 3. Output Switch Saturation Voltage vs Collector Current (Common-Emitter Configuration)

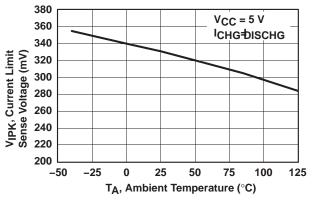


Figure 4. Current-Limit Sense Voltage vs Temperature

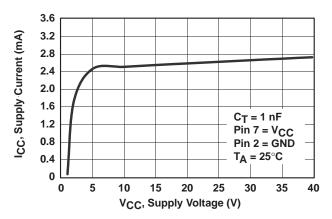
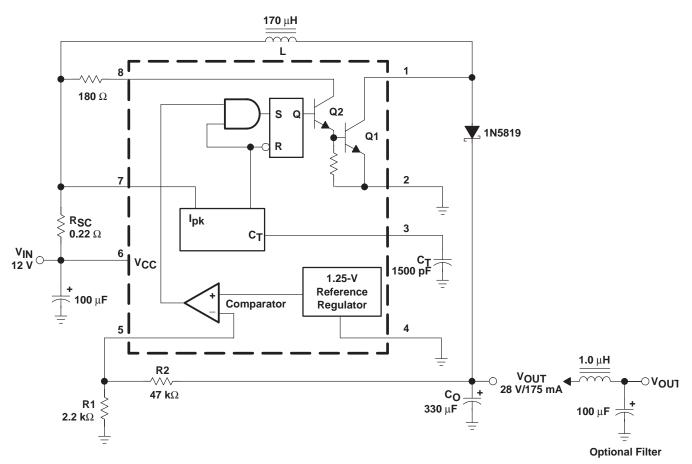


Figure 5. Standby Supply Current vs Supply Voltage



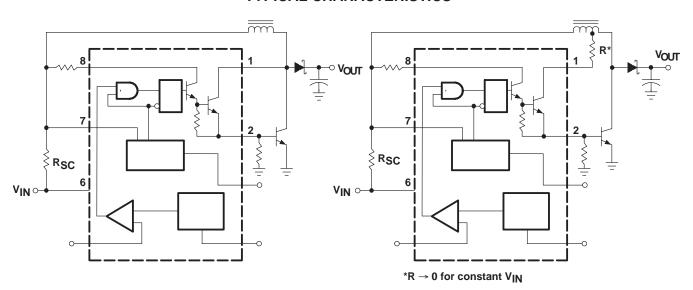


TEST	CONDITIONS	RESULTS
Line Regulation	$V_{IN} = 8 \text{ V to } 16 \text{ V, I}_{O} = 175 \text{ mA}$	30 mV ± 0.05%
Load Regulation	$V_{IN} = 12 \text{ V, I}_{O} = 75 \text{ mA to } 175 \text{ mA}$	10 mV ± 0.017%
Output Ripple	V _{IN} = 12 V, I _O = 175 mA	400 mVpp
Efficiency	V _{IN} = 12 V, I _O = 175 mA	87.7%
Output Ripple With Optional Filter	V _{IN} = 12 V, I _O = 175 mA	40 mVpp

Figure 6. Step-Up Converter

SLLS654A - APRIL 2005 - REVISED JANUARY 2007

TYPICAL CHARACTERISTICS



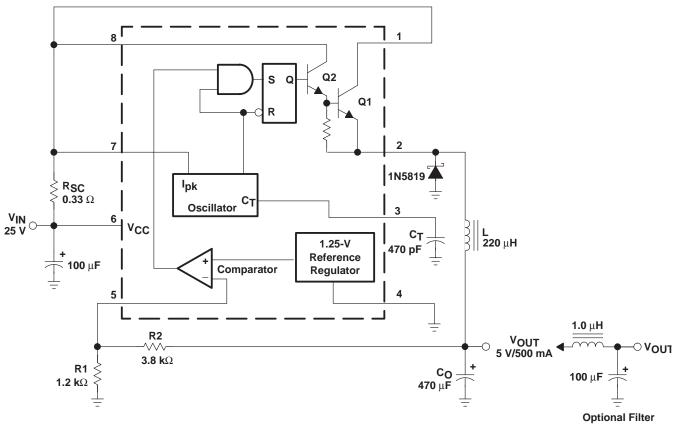
2a. External npn Switch

2b. External pnp Saturated Switch (see Note 5)

NOTE 5: If the output switch is driven into hard saturation (non-Darlington configuration) at low switch currents (≤300 mA) and high driver currents (≥30 mA), it may take up to 2 µs to come out of saturation. This condition will shorten the off time at frequencies ≥30 kHz and is magnified at high temperatures. This condition does not occur with a Darlington configuration because the output switch cannot saturate. If a non-Darlington configuration is used, the output drive configuration in Figure 2b is recommended.

Figure 7. External Current-Boost Connections for I_C Peak Greater Than 1.5 A





TEST	CONDITIONS	RESULTS
Line Regulation	V_{IN} = 15 V to 25 V, I_{O} = 500 mA	12 mV ± 0.12%
Load Regulation	$V_{IN} = 25 \text{ V}, I_{O} = 50 \text{ mA to } 500 \text{ mA}$	3 mV ± 0.03%
Output Ripple	V _{IN} = 25 V, I _O = 500 mA	120 mVpp
Short-Circuit Current	V_{IN} = 25 V, R_L = 0.1 Ω	1.1 A
Efficiency	V _{IN} = 25 V, I _O = 500 mA	83.7%
Output Ripple With Optional Filter	V _{IN} = 25 V, I _O = 500 mA	40 mV _{PP}

Figure 8. Step-Down Converter

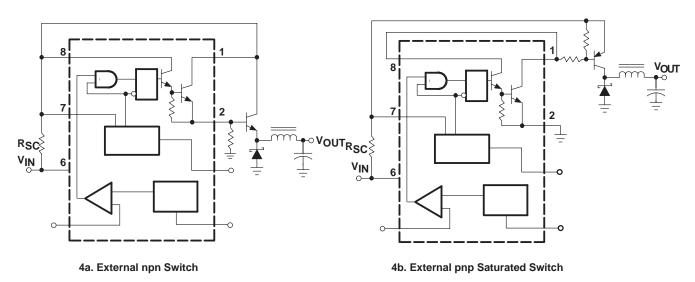
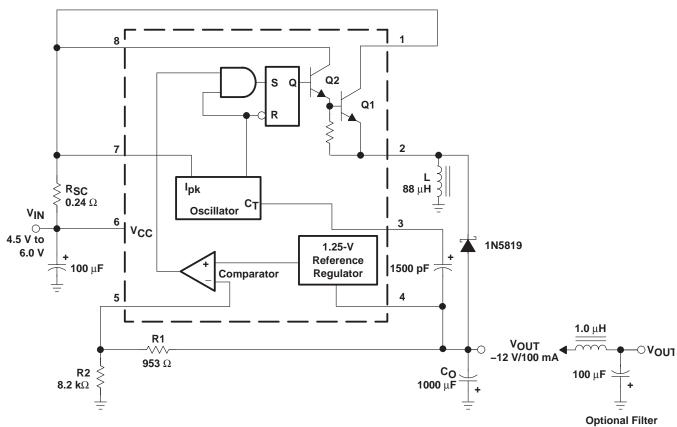


Figure 9. External Current-Boost Connections for I_C Peak Greater Than 1.5 A



		·
TEST	CONDITIONS	RESULTS
Line Regulation	V _{IN} = 4.5 V to 6 V, I _O = 100 mA	3 mV ± 0.12%
Load Regulation	$V_{IN} = 5 \text{ V}, I_{O} = 10 \text{ mA to } 100 \text{ mA}$	0.022 V ± 0.09%
Output Ripple	V _{IN} = 5 V, I _O = 100 mA	500 mVpp
Short-Circuit Current	$V_{IN} = 5 \text{ V}, R_L = 0.1 \Omega$	910 mA
Efficiency	V _{IN} = 5 V, I _O = 100 mA	62.2%
Output Ripple With Optional Filter	V _{IN} = 5 V, I _O = 100 mA	70 mVpp

Figure 10. Voltage-Inverting Converter

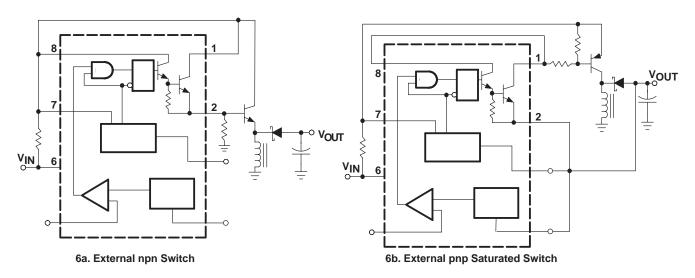


Figure 11. External Current-Boost Connections for $I_{\mbox{\scriptsize C}}$ Peak Greater Than 1.5 A



SLLS654A - APRIL 2005 - REVISED JANUARY 2007

APPLICATION INFORMATION

calculations of key parameters

CALCULATION	STEP UP	STEP DOWN	VOLTAGE INVERTING
ton/toff	$\frac{V_{\text{out}} + V_{\text{F}} - V_{\text{in(min)}}}{V_{\text{in(min)}} - V_{\text{sat}}}$	$\frac{V_{out} \; + \; V_{F}}{V_{in(min)} \; - \; V_{sat} \; - \; V_{out}}$	$\frac{ V_{out} + V_F}{V_{in} - V_{sat}}$
(t _{on} + t _{off})	1 f	<u>1</u>	<u>1</u> f
toff	$\frac{t_{\text{on}} + t_{\text{off}}}{\frac{t_{\text{on}}}{t_{\text{off}}} + 1}$	$\frac{t_{\text{on}} + t_{\text{off}}}{\frac{t_{\text{on}}}{t_{\text{off}}} + 1}$	$\frac{t_{\text{on}} + t_{\text{off}}}{\frac{t_{\text{on}}}{t_{\text{off}}} + 1}$
t _{on}	$(t_{on} + t_{off}) - t_{off}$	$(t_{on} + t_{off}) - t_{off}$	$(t_{on} + t_{off}) - t_{off}$
CT	$4 \times 10^{-5} t_{on}$	$4 \times 10^{-5} t_{on}$	$4 \times 10^{-5} t_{on}$
Ipk(switch)	$2I_{\text{out(max)}} \left(\frac{t_{\text{on}}}{t_{\text{off}}} + 1 \right)$	2I _{out(max)}	$2l_{out(max)} \left(\frac{t_{on}}{t_{off}} + 1 \right)$
R _{sc}	0.3 I _{pk(switch)}	0.3 I _{pk(switch)}	0.3 I _{pk(switch)}
L(min)	$\left(\frac{\left(V_{\text{in(min)}}-V_{\text{sat}}\right)}{I_{\text{pk(switch)}}}\right)\!t_{\text{on(max)}}$	$\left(\frac{\left(V_{in(min)} - V_{sat} - V_{out}\right)}{I_{pk(switch)}}\right)^{t_{on(max)}}$	$\left(\frac{\left(V_{in(min)} - V_{sat}\right)}{I_{pk(switch)}}\right) \! t_{on(max)}$
CO	9 Voutton Vripple(pp)	$\frac{I_{pk(switch)}(t_{on} + t_{off})}{8V_{ripple(pp)}}$	$9 \frac{I_{out}t_{on}}{V_{ripple(pp)}}$



PACKAGE OPTION ADDENDUM

29-Jan-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MC33063AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

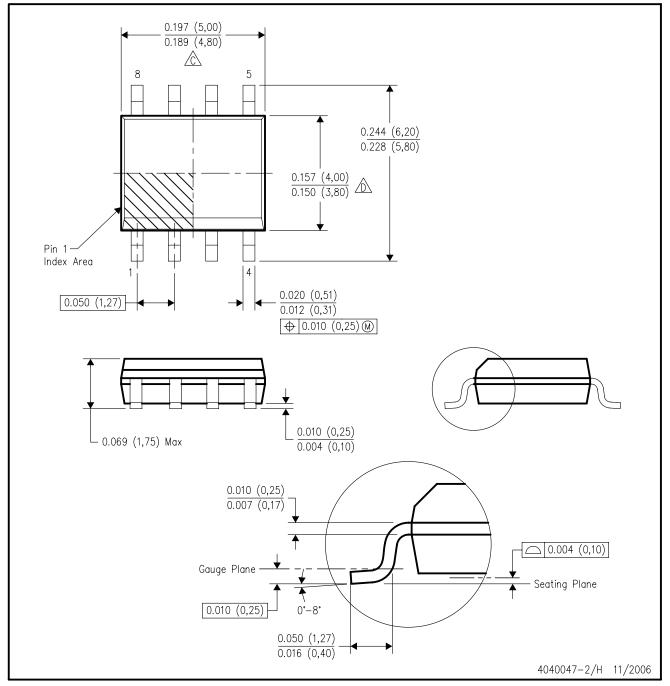
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



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